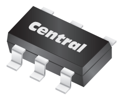
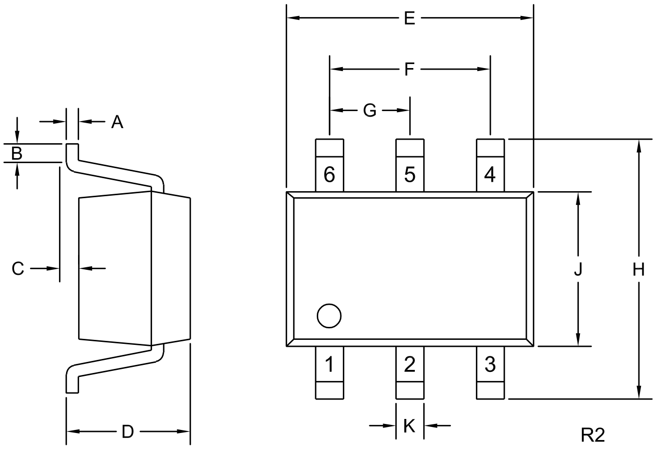
Package Details
SOT-363 Case



Mechanical Drawing



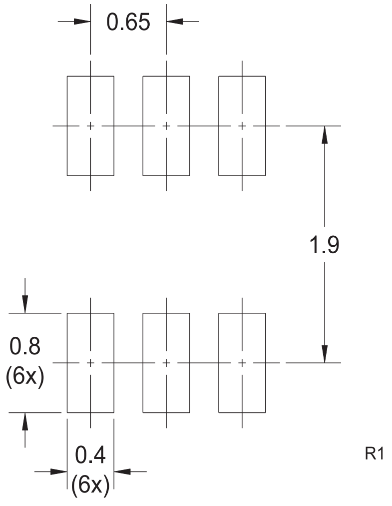
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.004	0.010	0.10	0.25
B	0.005	-	0.12	-
C	0.000	0.004	0.00	0.10
D	0.031	0.043	0.80	1.10
E	0.071	0.087	1.80	2.20
F	0.051		1.30	
G	0.026		0.65	
H	0.075	0.091	1.90	2.30
J	0.043	0.055	1.10	1.40
K	0.006	0.012	0.15	0.30

SOT-363 (REV: R2)

Lead Code:
Reference individual
device datasheet.

Part Marking: 3-4 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



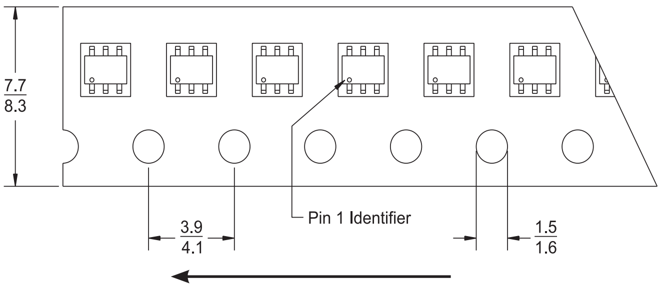
R3 (4-March 2010)

Package Details

SOT-363 Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

Packaging Base

7” Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

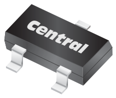
Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	27,000	9x9x5	23x23x13	3	2
	18	54,000	9x9x9	23x23x23	6	3
	40	120,000	21x9x9	53x23x23	13	6
	108	324,000	27x9x17	69x23x43	34	16

Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

Material Composition Specification

SOT-363 Case



Device average mass . . . . **5.9 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	3.38%	0.2	Si	7440-21-3	3.38%	0.2	33,841
bond wire	gold	0.68%	0.04	Au	7440-57-5	0.68%	0.04	6,768
leadframe	alloy 42 w/ silver plating	33%	1.95	Fe	7439-89-6	19.12%	1.13	191,201
				Ni	7440-02-0	13.2%	0.78	131,980
				Ag	7440-22-4	0.68%	0.04	6,768
encapsulation*	EMC	58.21%	3.44	silica	7631-86-9	41.96%	2.48	419,628
				epoxy resin	Proprietary	14.55%	0.86	145,516
				Sb_2O_3	1309-64-4	1.18%	0.07	11,844
				TBBA	79-94-7	0.34%	0.02	3,384
				carbon	1333-86-4	0.17%	0.01	1,692
	EMC GREEN	58.21%	3.44	silica	60676-86-0	38.9%	2.299	389,048
				epoxy resin	29690-82-2	8.84%	0.522	88,365
				phenol resin	9003-35-4	4.43%	0.262	44,333
				carbon black	1333-86-4	0.3%	0.018	3,016
				metal hydroxide	1309-42-8	5.73%	0.339	57,302
plating**	tin/lead process	4.74%	0.28	Sn	7440-31-5	3.98%	0.23	39,763
				Pb	7439-92-1	0.76%	0.04	7,614
	matte tin	4.74 %	0.28	Sn	7440-31-5	4.74%	0.28	47,377

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.